

10/519741
DT01 Rec'd PCT/P 28 DEC 2004

In the Claims:

1-20 (Canceled)

21. (New) A method of contacting parts of a component integrated into a semiconductor substrate, the method comprising:

providing a first contact hole in an insulating layer; and

filling the contact hole with contact material so that the contact material is electrically connected to a line;

wherein a hard mask that is used to probe the contact hole is also used to structure the line.